

Vintage: Dec. 2009

Wafer Size: 300mm

SW Version: 5.1.0.b

Main Process: Photo

Sub-Process: ARF-Scanner

(2) Hardware Configuration:

	Moudule	Check Items	Yes or No	Remarks
1	OIU	Is the motherboard complete?	✓	
2		Are the keyboard, mouse, and monitor working?	✓	
3	WH	Hardware defects or damage	X	
4		Are there any scratches or dirt on the component gripper or TSU surface?	X	
5	WS	Hardware defects or damage	✓	hover sensor valve connector damaged
6		Are there any scratches or dirt on the surface of the component Closing Disk?	X	attached on holder
7		Are there any scratches or dirt on the surface of the mirror block components?	X	
8		Are there any scratches or dirt on the Z-mirror component surface?	✓	water stain
9		Are there any scratches or dirt on the surface of the image sensor components?	X	
10		Are there any scratches or dirt on the surface of the wafer table component?	X	wafer on table
11	RH	Hardware defects or damage	X	
12	RS	Hardware defects or damage	X	
13		Are there any scratches or dirt on the R-chuck component surface?	X	A little bit of particle
14	ILL	Hardware defects or damage	X	
15		Does the surface of the REMA lens have any scratches or dirt?	X	
16		Is there a number of Bending Points?	X	

17	Lens	Hardware defects or damage	X	
18		Are there any scratches or dirt on the top and bottom of the lens?	X	
19		Is the sensor on the top of the lens complete?	✓	
20	EIM	Hardware defects or damage?	X	
21		Hardware defects or damage?	✓	295
22	LMA&AOM	Hardware defects or damage?	X	
23	ELEC	Hardware defects or damage?	X	
24	WSRC	Hardware defects or damage?	X	
25	RSRC	Hardware defects or damage?	X	
26	ACC	Hardware defects or damage?	X	
27	LCWC	Hardware defects or damage?	X	
28	MCWC	Hardware defects or damage?	X	
29	WICC	Hardware defects or damage?	X	
30	WISC	Hardware defects or damage?	X	
31	Laser	Hardware defects or damage?	X	MODEL: Cymer XLA360 2005 10/31

(3) Status of System:

System safely powered down_

SECS Control:	Date: 2026/7/1	Screen Control:	Enable	Disable	User: ASML
SECS Comm.:	Time:		OK	NG	Level: SERVICE ENG.
Status: Start Up Drivers					
Imaging		Metrology		Production Control	Start Up
Imaging Scan Control: Terminated		Light & Tilt Control (E): Terminated		Expose Control: Terminated	Drivers
Illumination: Terminated		Coord. System Control-wafer: Terminated		Expose Scan Control: Terminated	
Projection: Terminated		Image Quality Control: Terminated		Swap Control: Terminated	
Dose Control: Terminated		Light & Tilt Control (M): Terminated		Measure Control: Terminated	Maintenance
Rema Control: Terminated		Coord. System Control-blue: Terminated		Route Control: Terminated	Drivers
Pressure Temperature Control: Terminated		Metrology Driver: Terminated		Maintenance Scheduler: Terminated	
Wet Imaging Control: Terminated					
Wafer Alignment & Levelling		Image Alignment & Quality		Support	Shut Down
Level Scan Control: Terminated		Image Sensor Scan Control: Terminated		Synchronisation (M): Terminated	Drivers
Level Sensor: Terminated		Image Sensor sub-system: Terminated		Synchronisation (E): Terminated	
Alignment Scan Control: Terminated		ILIAS Scan Control: Terminated		System Interferometers: Terminated	
Alignment Subsystem: Terminated		ILIAS sub-system: Terminated		Temperature Control: Terminated	System
Mark Type Database: Terminated		Polarization Scan Control: Terminated		Air Mounts: Terminated	
				Water Table Cleaning: Terminated	System and UNIX
Wafer Flow		Reticle Flow			Referesh
Stages Scan Control: Terminated		Reticle Stage: Terminated			Driver
Wafer Stage: Terminated		Reticle Handler: Terminated			Status
Water Handler: Terminated		Reticle Logistics: Terminated			
Wafer Logistics: Terminated					
Start Up Drivers: Terminated		Task/Host Monitor	Initialized	Busy	M=Measure
0%			Terminated	Failed	E=Expose
*Pay attention: If it's immersion model, the exposure should be switched to WET mode.					
*Pay attention to the positions of the immersion hood and the closing disk.					

(4) System Acceptance Test:

Full dynamic testing omitted due to the tool's safely decommissioned status and utility isolation;
comprehensive initialization and calibration deferred to the final installation phase

TWINSKAN XT:1700Fi SYSTEM ACCEPTANCE TESTS

Category		Items	Spec	Model: XT1700Fi
Full Acceptance Test			XT1700Fi	Result-Data
1. Overlay	1.1 Single machine overlay		≤ 5	NA
2. Intensity	2.1 Slit integrated power, 11 scans in 26mm Setting 1 [mW/cm]		$\geq 1650^{**}$	NA
3. Projection Lens	3.1 RMS Z5-Z37 [nm]		≤ 1.4	2.03
	3.2 RMS Spherical [nm]		≤ 0.8	0.88
	3.3 RMS coma [nm]		≤ 0.8	0.46
	3.4 RMS astigmatism [nm]		≤ 0.8	0.55
	3.5 RMS 3-foil [nm]		≤ 0.8	0.56
	3.6 Long range straylight [SAMOS %]		≤ 0.9	NA
	3.7 Short range straylight [SAMOS %]		≤ 1.2	NA
4. Illumination	4.1 Dose system performance, setting 1 [%]		≤ 1.0	NA
	4.2 Integrated slit uniformity, setting 1 [%]		≤ 0.30	NA
	4.3 Integrated scan uniformity, setting 1 [%]		≤ 0.2	NA
	4.4 Dose repeatability [%]		≤ 0.2	NA
	4.5 Dose accuracy setting 1 [%]		± 0.7	NA
5. Pupil Verification	5.1 Ellipticity, Setting 1 [meam]		≤ 1.5	NA
	5.2 Sigma variation setting 1 [range]		≤ 0.007	NA
6. Focus and Leveling	6.1 Wafer map repeatability (99.7%) [nm]		≤ 8	NA
7. Dynamic Performance	7.1 MA X&Y (mean+3ig) [nm]		≤ 2.0	NA
	7.2 MSD X&Y (max of mean per field) [nm]		≤ 6.5	NA
	7.3 Inspection time (<200 particles found) [nm]		≤ 225	NA
	7.4 Size accuracy - lates spheres () Upper surface			
	10um [um]		± 3	NA
	30um [um]		± 3	NA
	50um [um]		± 5	NA
	7.5 Size accuracy - latex spheres () Lower surface			
	10um [um]		± 3	NA
	30um [um]		± 3	NA
	50um [um]		± 5	NA
8. BMWL - fine	Test results			NA
9. TSPE	Test results			NA
10. SWZS	Test results			NA